

IN THE SPECIFICATION

Please amend the paragraph bridging lines 12-25 on page 9 (paragraph [0027] of the printed publication), as follows:

On the contrary, the pad portion 5B of the lead 5 is in the situation that the substantial half of the pad surface is exposed in the device mounting portion 1A on the one surface side of the housing 1 and that the substantial half of the pad surface is also exposed in the device mounting portion 1B. However, the exposed portion of the pad 5B on one surface side of the housing 1 and the exposed portion of the pad portion 5B on the other surface side of the housing 1 are in the position relation different from each other, and thus are not coincident. That is, the pad portion 5B of the lead 5 ~~is-has a portion of one side exposed to the device mounting portions portion 1A and a non-coincident portion on the other side exposed to the device mounting portion 1B~~ in the position relation alternate with each other, on the one surface side and other surface side of the housing 1, and ~~this-these~~ exposed ~~portion serves~~portions can serve as the connection portion ~~by the~~for wire bonding.